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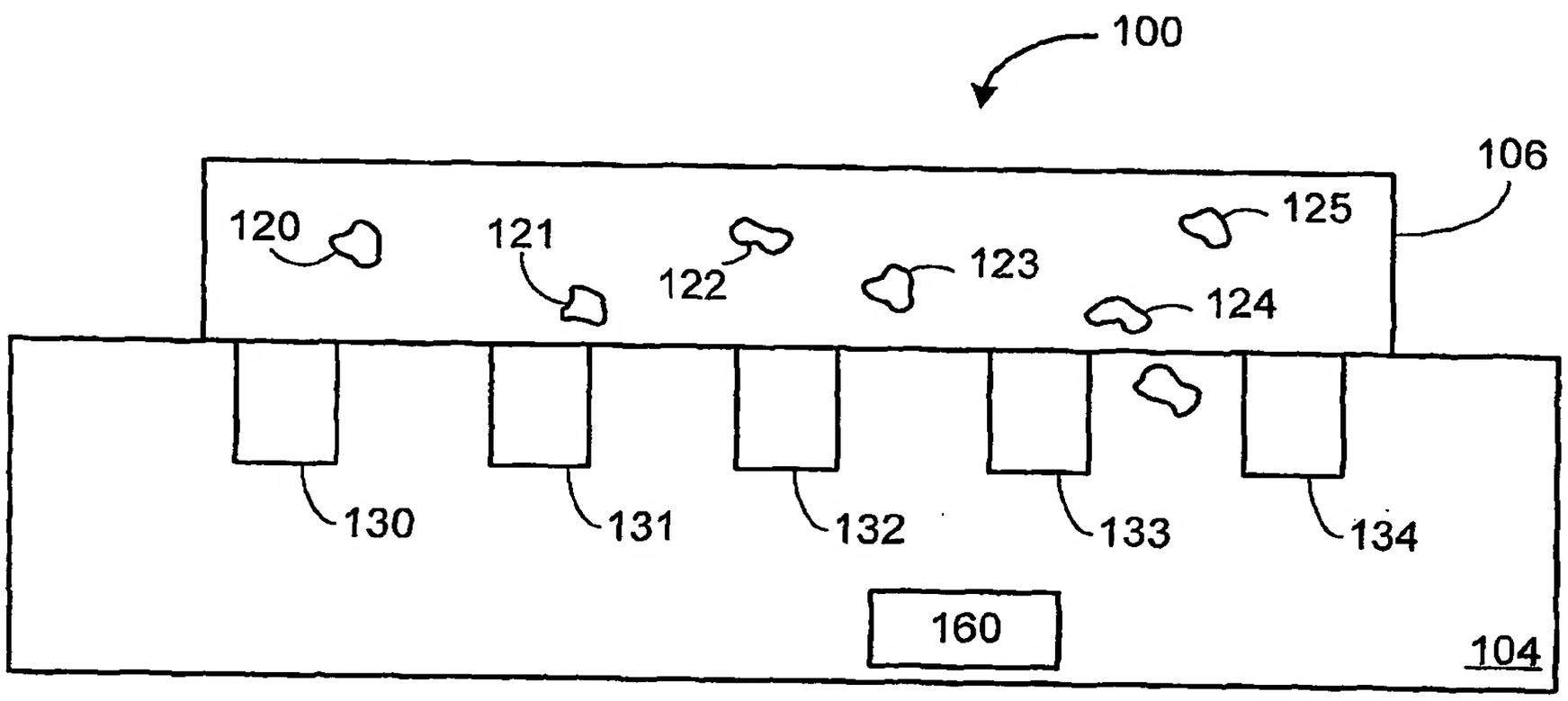
*[Continued on next page]*

(54) Title: TAMPER-RESISTANT PACKAGING AND APPROACH




(57) Abstract: A tamper-resistant packaging approach protects non-volatile memory (108). According to an example embodiment of the present invention, a package (106) having a plurality of magnetic particles (120-125) therein is arranged with an integrated circuit device (100) to cause a plurality of magnetically-responsive circuit nodes (130-134) to take on magnetic states. Each magnetic state is detected as a logic state, and then compared with a real-time logic state of the magnetically-responsive circuit nodes and, in response to a stored logic state being different from a real-time logic state, package tampering is detected. In one instance, tampering is detected when the magnetic state of one of the magnetically-responsive circuit nodes is altered as a portion of the package is removed. The detected tampering may alter a characteristic of the integrated circuit, such as by altering stored data or setting a tamper flag that indicates the package has been tampered with.

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